

KB-1150 (ANSI: XPC/ JIS: PP7)

纸芯覆铜基板

Features 特点

- Low cost but with wide range of applications
成本低而使用范围广
- Warpage and twist are small and stable
弯曲度、扭曲度小且稳定
- Suitable for punching at 40 ~ 70°C
适合之冲孔温度为 40 ~ 70°C

General Properties 一般特性

Test Item 测试项目	Unit 单位	Test Condition 处理条件	Testing Method 测试方法	Specification 规格值	Typical Value 典型值
Thermal 热性能					
Solder Resistance (float 260°C) 耐焊性	Sec	A	JIS C 6481	≥ 10	15 ~ 30
Heat Resistance 耐热性	—	130°C 30min	JIS C 6481	No Change 无异常	No Change 无异常
Flammability 阻燃性	Rating	A	UL94	HB	HB
Electrical 电性能					
Volume Resistivity 体积阻抗系数	Ω-cm	C-96/20/65 C-96/20/65+C-96/40/90	JIS C 6481	5×10 ⁹ 5×10 ⁸	1×10 ¹² ~10 ¹³ 1×10 ¹⁰ ~10 ¹¹
Surface Resistivity 表面抗阻	Adhesive Side 粘接剂面	C-96/20/65 C-96/20/65+C-96/40/90	JIS C 6481	1×10 ¹⁰ 1×10 ⁹	1×10 ¹¹ ~10 ¹² 1×10 ¹⁰ ~10 ¹¹
	Laminate Side 积层板面	C-96/20/65 C-96/20/65+C-96/40/90		1×10 ⁹ 1×10 ⁷	1×10 ¹⁰ ~10 ¹¹ 1×10 ⁹ ~10 ¹⁰
Insulation Resistance 绝缘抗阻	Ω	C-96/20/65 C-96/20/65+D-2/100	JIS C 6481	1×10 ⁹ 1×10 ⁶	1×10 ¹⁰ ~10 ¹¹ 1×10 ⁷ ~10 ⁸
Dielectric Constant (1 MHz) 介电常数 (1 MHz)	—	C-96/20/65 C-96/20/65+D-24/23	JIS C 6481	≤5.5 ≤6.0	4.0~5.0 4.5~5.5
Dissipation Factor 介质损耗因子	—	C-96/20/65 C-96/20/65-D-24/23	JIS C 6481	≤0.05 ≤0.1	0.025~0.035 0.035~0.045
CTI Value CTI 值	V	0.1% NH4CL	IEC 60112	≥150	150 ~175
Mechanical 机械性能					
Peel Strength (Copper Foil 35μm) 铜箔剥离强度 (35μm 铜箔)	Kgf/cm	A float 260°C/5 Sec	JIS C 6481	≥ 1.2	1.4 ~ 1.7 1.4 ~ 1.7
Flexural Strength 弯曲强度	Lengthwise 纵向	A	JIS C 6481	≥ 8	14~16 13~14
	Crosswise 横向				
Chemical Resistance 耐化学性	—	3% NaOH 40°C 3min	JIS C 6481	No change 无异常	No change 无异常
		Boiled in trichloroethylene for 3 min		No change 无异常	No change 无异常
Moisture Absorption 吸水率	%	E-24/50+D-24/23	JIS C 6481	≤2	1.0 ~ 1.5
Punching Temperature 冲孔温度	°C	A	GB/T4722	40 - 70	40 - 70

Remarks :

Specimen Thickness: 1.6 mm 样品厚度 : 1.6 mm

Typical values for reference only 典型值只作参考

Stand values according to JIS-C-6485 规格值参照 JIS-C-6485

A = Keep the specimen originally without any process 保持原样,不作处理

C = Temperature and humidity conditioning 在恒温恒湿的空气中处理

D = Immersing in distilled water with temperature control 浸在恒温的水中处理

E = Temperature conditioning 在恒温的空气中处理